<table>
<thead>
<tr>
<th>ALL NETS ISOLATED FROM TOP SIDE</th>
<th>BOARD No. TIPN-03365</th>
<th>REI &amp; REII</th>
<th>SMT REI No. In HorizonControl</th>
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</thead>
<tbody>
<tr>
<td>LAYER NAME = GND</td>
<td>T10 A1</td>
<td>TIPN-03365</td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Signal Layer 1</td>
<td>GENERATED</td>
<td>1-1-2017</td>
<td>10-27-1210 1010 TEXAS INSTRUMENTS</td>
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